Octal D Flip-Flop with Clear

The SN74LS273 is a high-speed 8-Bit Register. The register consists of eight D-Type Flip-Flops with a Common Clock and an asynchronous active LOW Master Reset. This device is supplied in a 20-pin package featuring 0.3 inch lead spacing.

- 8-Bit High Speed Register
- Parallel Register
- Common Clock and Master Reset
- Input Clamp Diodes Limit High-Speed Termination Effects

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Тур	Max	Unit
VCC	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	°C
ІОН	Output Current – High			-0.4	mA
loL	Output Current – Low			8.0	mA



ON Semiconductor

http://onsemi.com

LOW POWER SCHOTTKY

MARKING DIAGRAMS













A = Assembly Location

WL = Wafer Lot YY = Year

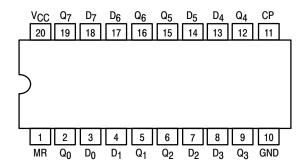
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping	
SN74LS273N	PDIP-20	1440 Units/Box	
SN74LS273DW	SOIC-WIDE	38 Units/Rail	
SN74LS273DWR2	SOIC-WIDE	2500/Tape & Reel	
SN74LS273M	SOEIAJ-20	See Note 1.	
SN74LS273MEL	SOEIAJ-20	See Note 1.	

 For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

CONNECTION DIAGRAM DIP (TOP VIEW)



PIN NAMES

HIGH LOW CP Clock (Active HIGH Going Edge) Input 0.5 U.L. 0.25 U.L. Data Inputs 0.5 U.L. 0.25 U.L. <u>D</u>0 - D₇ MR Master Reset (Active LOW) Input 0.5 U.L. 0.25 U.L. $Q_0 - Q_7$ Register Outputs 10 U.L. 5 U.L.

LOADING (Note a)

NOTES:

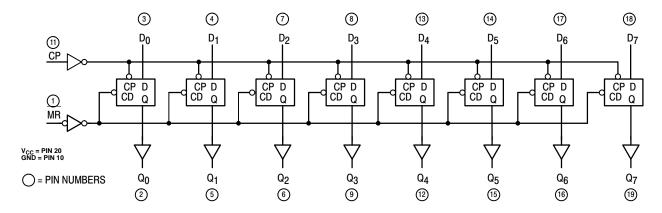
a) 1 TTL Unit Load (U.L.) = 40 μ A HIGH/1.6 mA LOW.

TRUTH TABLE

MR	СР	D _X	$Q_{\mathbf{X}}$
Г	Χ	Χ	L
Н	\neg	Н	Н
Н		L	L

H = HIGH Logic Level L = LOW Logic Level X = Immaterial

LOGIC DIAGRAM



FUNCTIONAL DESCRIPTION

The SN74LS273 is an 8-Bit Parallel Register with a common Clock and common Master Reset.

When the MR input is LOW, the Q outputs are LOW, independent of the other inputs. Information meeting the

setup and hold time requirements of the D inputs is transferred to the Q outputs on the LOW-to-HIGH transition of the clock input.

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

			Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Tes	t Conditions
VIH	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V _{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
VIK	Input Clamp Diode Voltage		-0.65	-1.5	V	$V_{CC} = MIN, I_{IN} = -18 \text{ mA}$	
Vон	Output HIGH Voltage	2.7	3.5		V	V _{CC} = MIN, I _{OH} = MAX, V _{IN} = V _{IH} or V _{IL} per Truth Table	
V	V _{OL} Output LOW Voltage		0.25	0.4	V	I _{OL} = 4.0 mA	V _{CC} = V _{CC} MIN,
VOL			0.35	0.5	V	I _{OL} = 8.0 mA	V _{IN} = V _{IL} or V _{IH} per Truth Table
l	Innut I II CI I Current			20	μΑ	V _{CC} = MAX, V _{IN}	= 2.7 V
ΊΗ	Input HIGH Current			0.1	mA	V _{CC} = MAX, V _{IN} = 7.0 V	
I _I L	Input LOW Current			-0.4	mA	V _{CC} = MAX, V _{IN} = 0.4 V	
los	Short Circuit Current (Note 2.)	-20		-100	mA	V _{CC} = MAX	
ICC	Power Supply Current			27	mA	V _{CC} = MAX	

^{2.} Not more than one output should be shorted at a time, nor for more than 1 second.

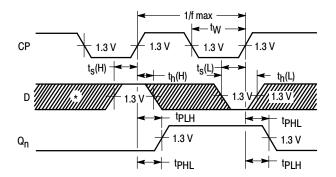
AC CHARACTERISTICS ($T_A = 25$ °C, $V_{CC} = 5.0 \text{ V}$)

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
fMAX	Maximum Input Clock Frequency	30	40		MHz	Figure 1
t _{PHL}	Propagation Delay, MR to Q Output		18	27	ns	Figure 2
^t PLH ^t PHL	Propagation Delay, Clock to Output		17 18	27 27	ns	Figure 1

AC SETUP REQUIREMENTS (TA = 25° C, V_{CC} = 5.0 V)

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
t _W	Pulse Width, Clock or Clear	20			ns	Figure 1
t _S	Data Setup Time	20			ns	Figure 1
t _h	Hold Time	5.0			ns	Figure 1
t _{rec}	Recovery Time	25			ns	Figure 2

AC WAVEFORMS



^{*}The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 1. Clock to Output Delays, Clock Pulse Width, Frequency, Setup and Hold Times Data to Clock

DEFINITION OF TERMS

SETUP TIME (t_S) — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW-to-HIGH in order to be recognized and transferred to the outputs.

HOLD TIME (th) — is defined as the minimum time following the clock transition from LOW-to-HIGH that the logic level must be maintained at the input in order to ensure

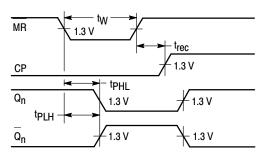


Figure 2. Master Reset to Output Delay, Master Reset Pulse Width, and Master Reset Recovery Time

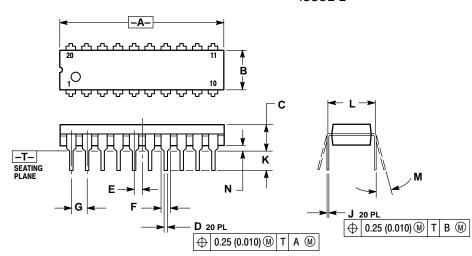
continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW-to-HIGH and still be recognized.

RECOVERY TIME (t_{rec}) — is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW-to-HIGH in order to recognize and transfer HIGH data to the Q outputs.

PACKAGE DIMENSIONS

N SUFFIX

PLASTIC PACKAGE CASE 738-03 ISSUE E

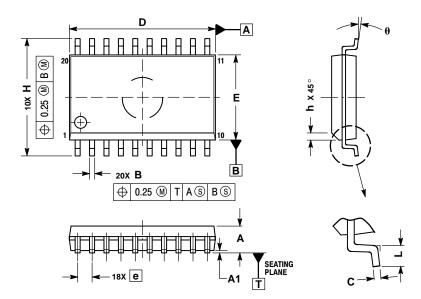


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INC	HES	MILLIMETERS		
DIM	MIN	MIN MAX		MAX	
Α	1.010	1.070	25.66	27.17	
В	0.240	0.260	6.10	6.60	
С	0.150	0.180	3.81	4.57	
D	0.015	0.022	0.39	0.55	
E	0.050	BSC	1.27 BSC		
F	0.050	0.070	1.27	1.77	
G	0.100	BSC	2.54 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.140	2.80	3.55	
L	0.300 BSC		7.62 BSC		
M	0 °	15°	0°	15°	
N	0.020	0.040	0.51	1.01	

PACKAGE DIMENSIONS

D SUFFIX PLASTIC SOIC PACKAGE CASE 751D-05 ISSUE F



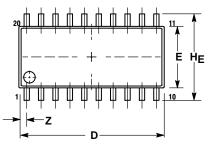
- NOTES:
 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

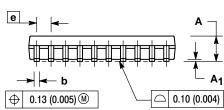
	MILLIMETERS					
DIM	MIN	MAX				
Α	2.35	2.65				
A1	0.10	0.25				
В	0.35	0.49				
С	0.23	0.32				
D	12.65	12.95				
Е	7.40	7.60				
е	1.27	BSC				
Н	10.05	10.55				
h	0.25	0.75				
L	0.50	0.90				
A	0 °	7 °				

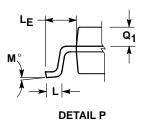
PACKAGE DIMENSIONS

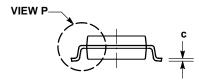
M SUFFIX

SOEIAJ PACKAGE CASE 967-01 **ISSUE O**









NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) BED RIPE.
- PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
 PER SIDE.
 TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT I FAD BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
Α ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.18	0.27	0.007	0.011	
D	12.35	12.80	0.486	0.504	
Е	5.10	5.45	0.201	0.215	
е	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
M	0 °	10 °	0 °	10°	
Q ₁	0.70	0.90	0.028	0.035	
Z		0.81		0.032	

SN741 S273

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